

Timing resolution on an irradiated 3D silicon pixel detector



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Outline

- Needs timescale 10 y
- 3D Pixel Sensor CNM Production
- Experimental Setup
- 3D Time resolution before and after irradiation for 285 μm thick sensor at -20°C

Needs on timescale 10y



Fixed targets

- NA61 Shine (beam monitor – measurement of each beam particle; p to Pb) (40 ps, 250 μm position resolution)

Rare decays

- NA62 (high intensity Kaon program at SPS)
 - GigaTracker upgrade (20-40 ps, ~few 100x100 μm²), $2 \cdot 10^{13}$ p on target/3s spill, extremely good efficiency required

Linear e-e machines

- Tracking: ~5 ns timing, but extremely low mass and position resolution (few μm)
- Forward Calorimetry: optional/beyond baseline (required GaAs/Si) to reduce the timing <1ns

Post LS3 LHC ($\Phi_{eq} > 10^{16}$ cm⁻²)

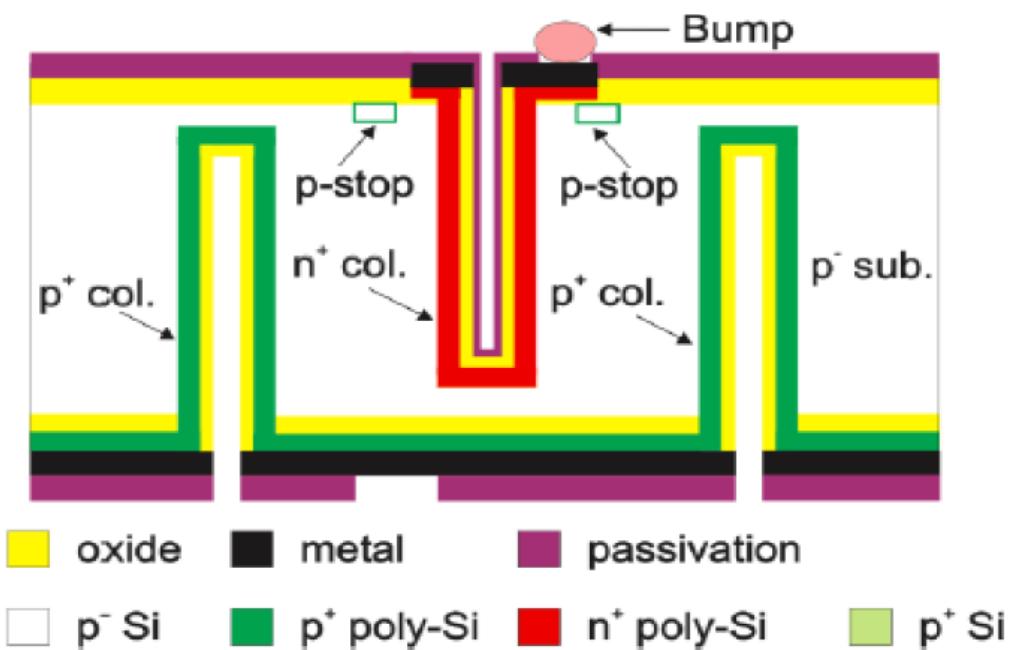
- LHC-B Velo II upgrade (>LS4)
 - $L = 1.5 \cdot 10^{34}$ cm⁻²s⁻¹ (7.5x occ.) , max fluence $5 \cdot 10^{16}$ cm⁻² with huge fluence spread over the sensor -> desired full 4D tracking
 - ~55 μm pitch, <50 ps/hit resolution (ongoing optimization)
- CMS (LS >4,5)
 - possible addition of pixel disks with high precision timing in the forward region (~100x100 μm², ~30 ps)
- ATLAS (LS >4,5)
 - replacement of LGADs in the inner rings of HGTD
 - replacement of the inner-most pixel layers with possible timing information <50ps

3D Pixel Sensor – CNM production

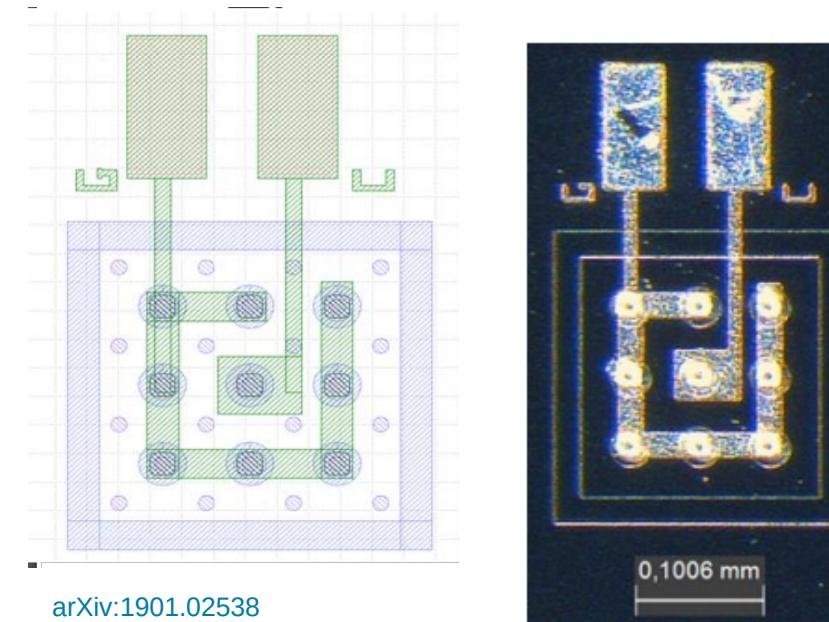
Features:

- thickness: $285\mu\text{m}$
- cell size: $50 \times 50 \mu\text{m}^2$
- p-type bulk resistivity: $\sim 5\text{k}\Omega\text{cm}$
- diameter holes: $8-10 \mu\text{m}$

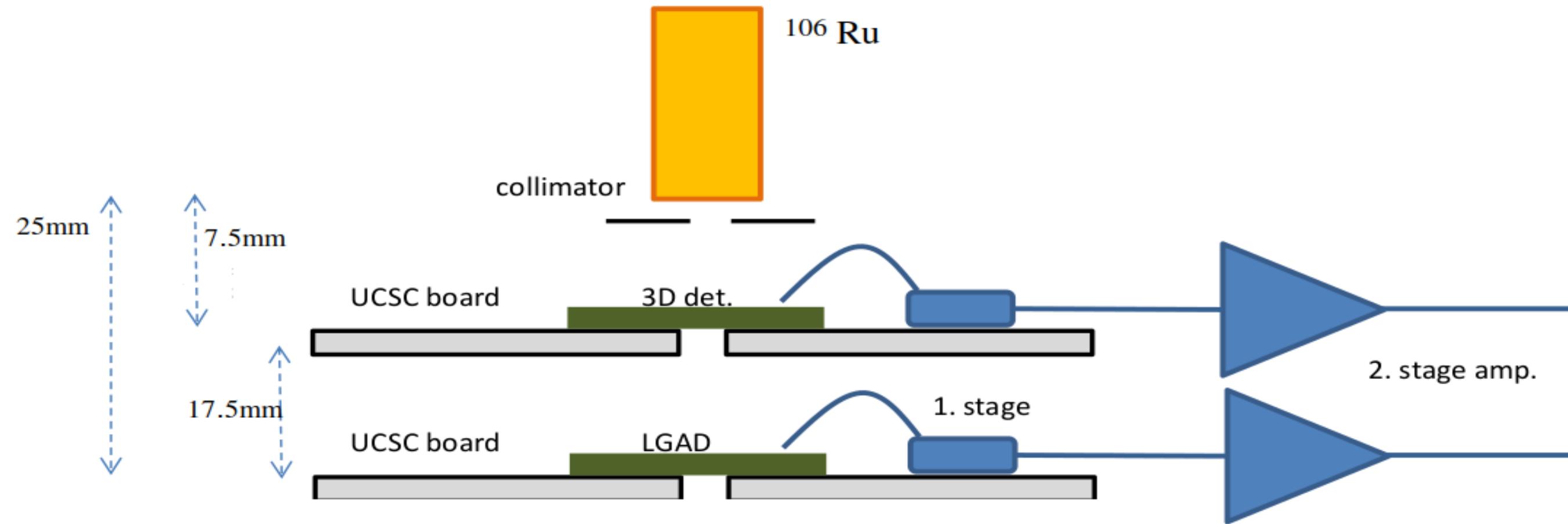
Schematic Cross Section



Design of a single cell structure



Experimental Setup



Signals in coincidence are analyzed

Source: ^{106}Ru

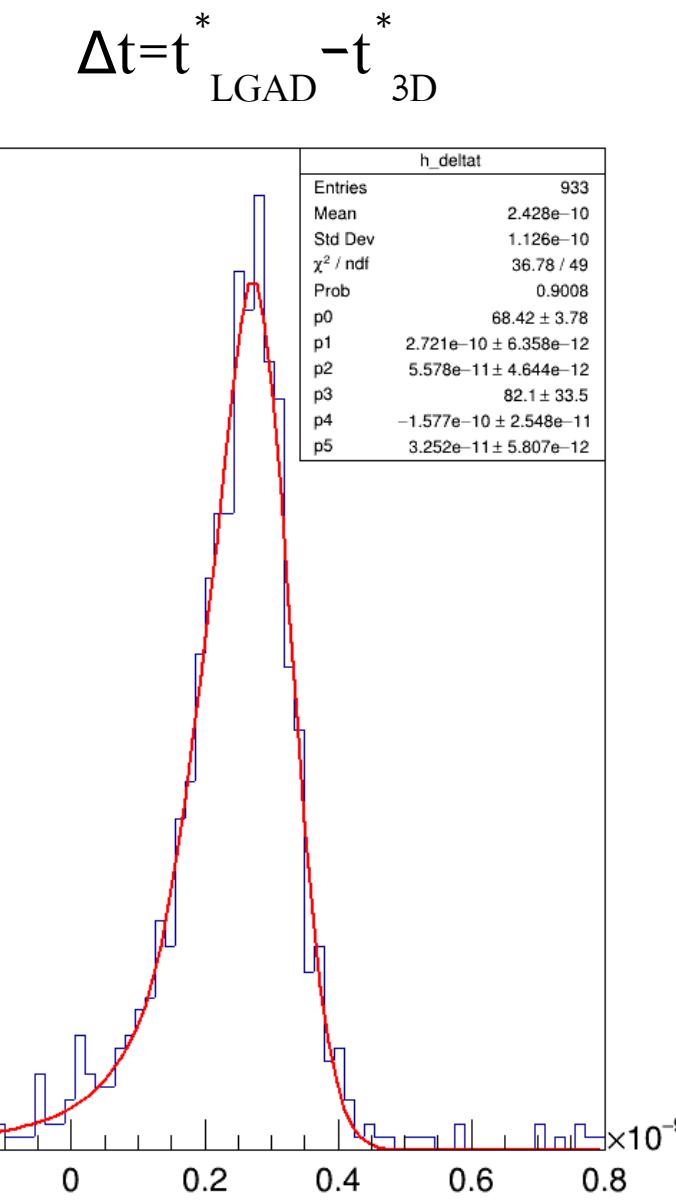
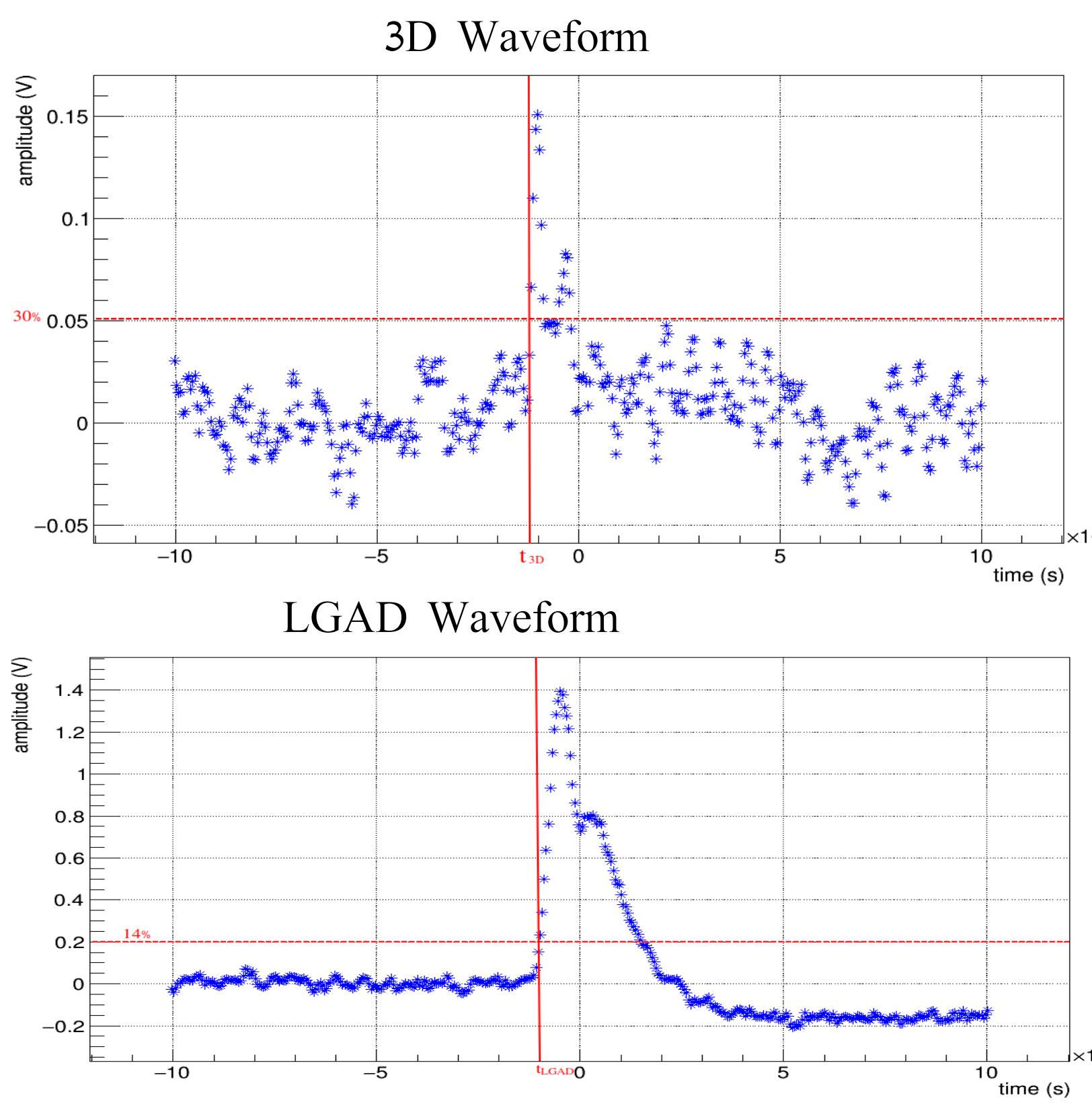
Board: Preamplified UCSC

LGAD: HPK50C - high gain 50 μm thick (1 mm diameter)
Time resolution 39 ps (20°C) and 36 ps (-20°C)

2.stage amp: 4GHz

Readout: Waverunner 8404M oscilloscope 4GHz

3D Waveform and analysis - σ_{3D}

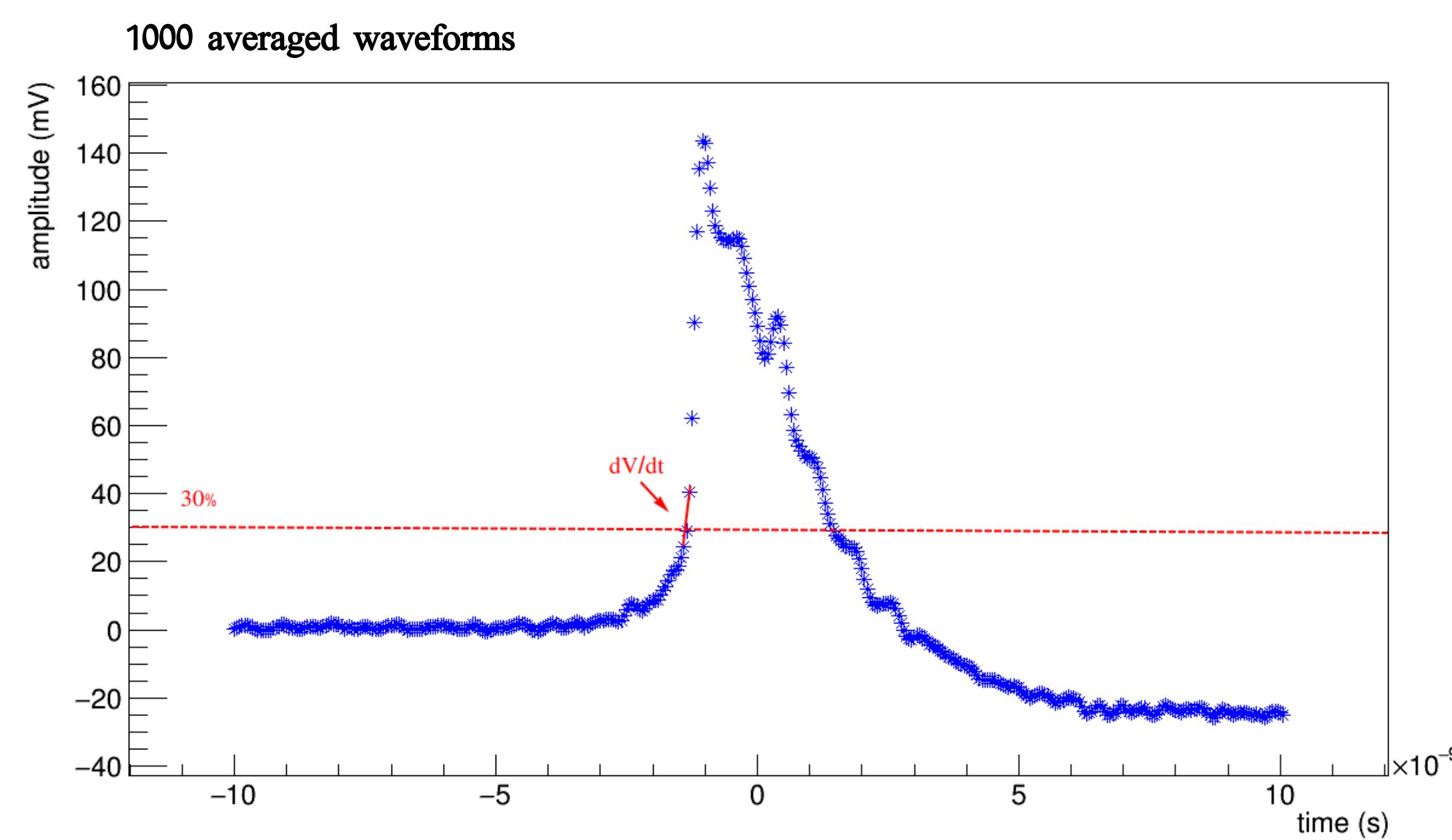


Fit on Δt to obtain: $\sigma_t = (\sigma_{\text{LGAD}}^2 + \sigma_{\text{3D}}^2)^{1/2}$

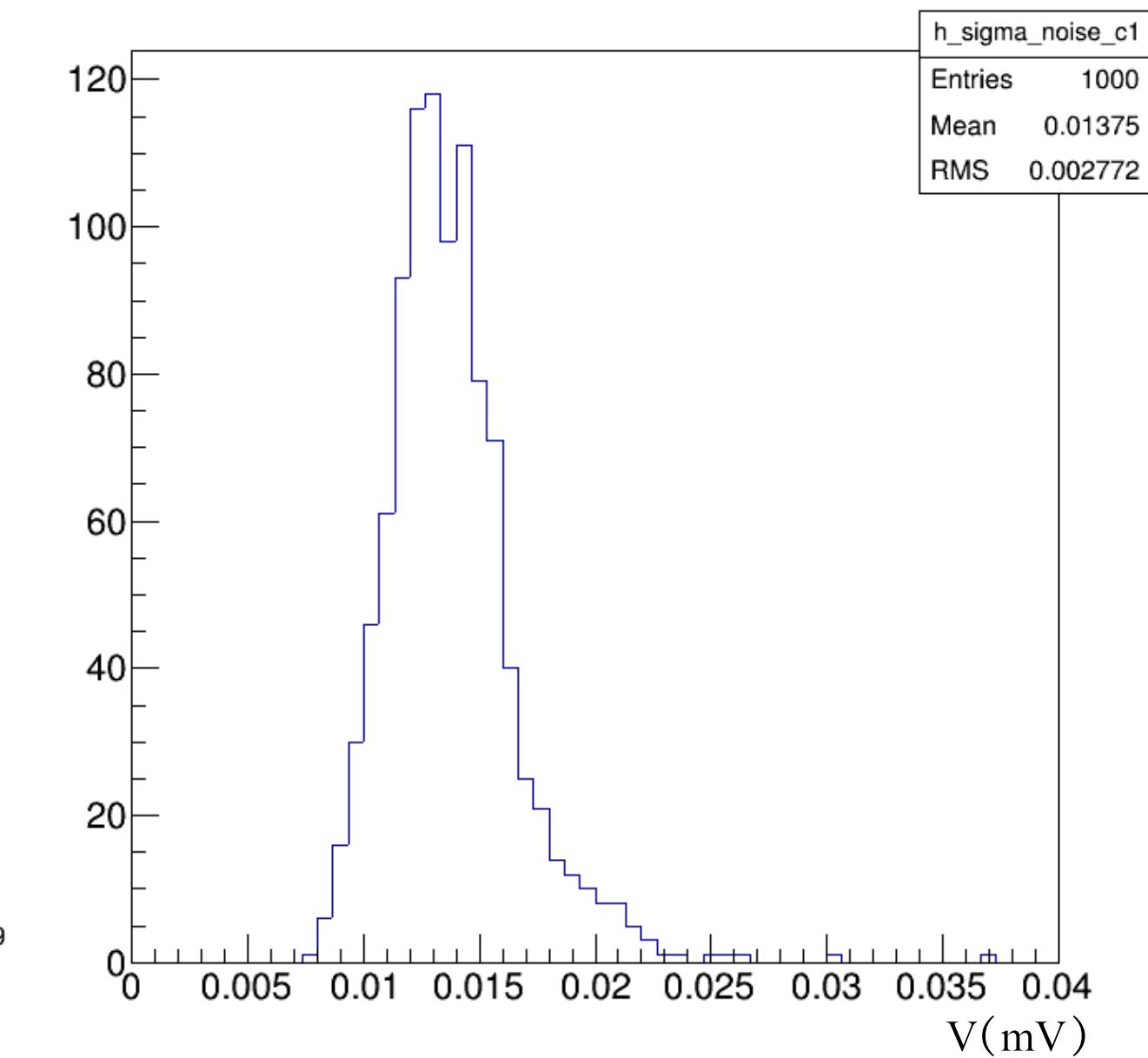
$$\sigma_{\text{wf}}^2 \approx \sigma_{\text{3D}}^2 - \sigma_{j,3D}^2$$

3D Waveform and analysis - σ_j

$$\sigma_{\text{wf}}^2 \approx \sigma_{\text{3D}}^2 - \sigma_{j,\text{3D}}^2$$



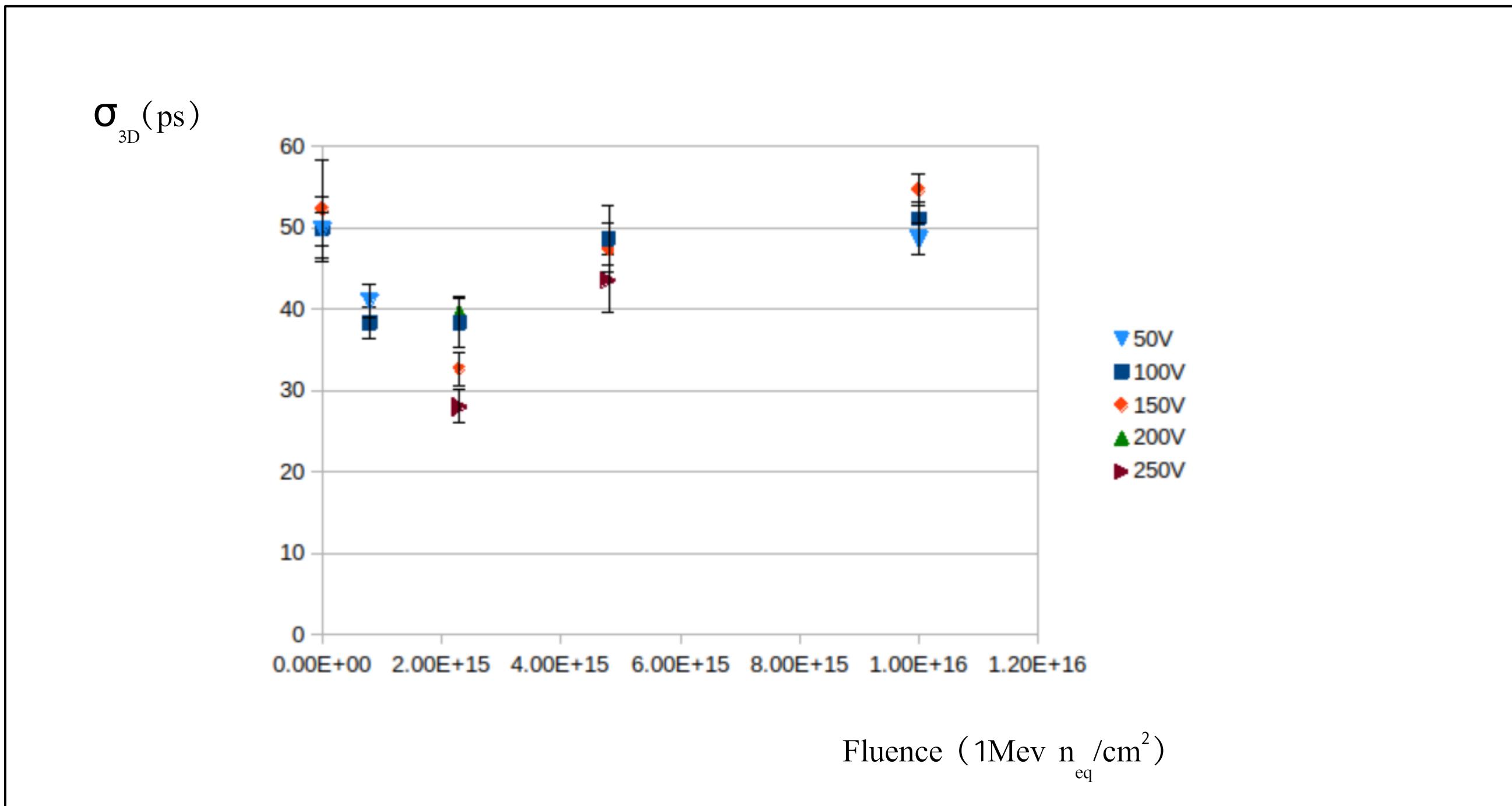
RMS of the noise



3D time resolution at -20°C VS Fluence

Annealed 60 min at 80°C

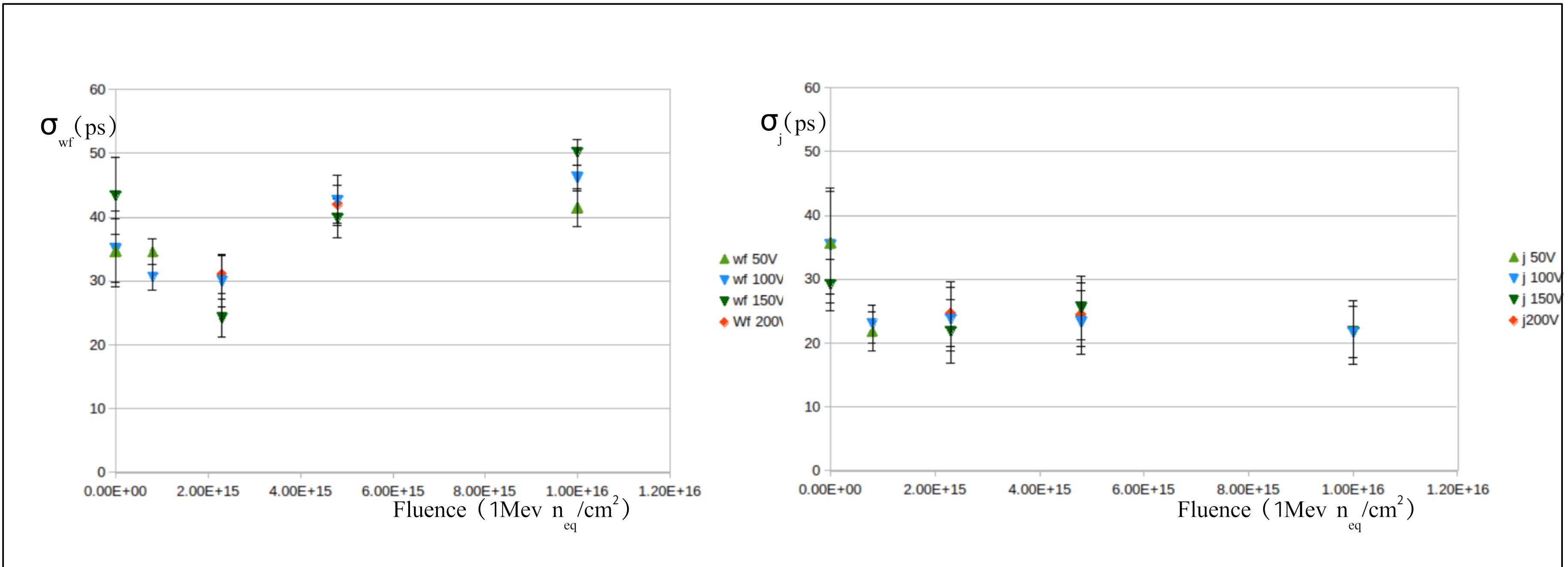
Irradiated at 8×10^{14} 1Mev n_{eq}/cm^2 - 2.3×10^{15} 1Mev n_{eq}/cm^2 - 4.8×10^{15} 1Mev n_{eq}/cm^2 - 1.0×10^{16} 1Mev n_{eq}/cm^2 at Ljubljana



Weighting field and jitter at -20°C VS fluence

Annealed 60 min at 80°C

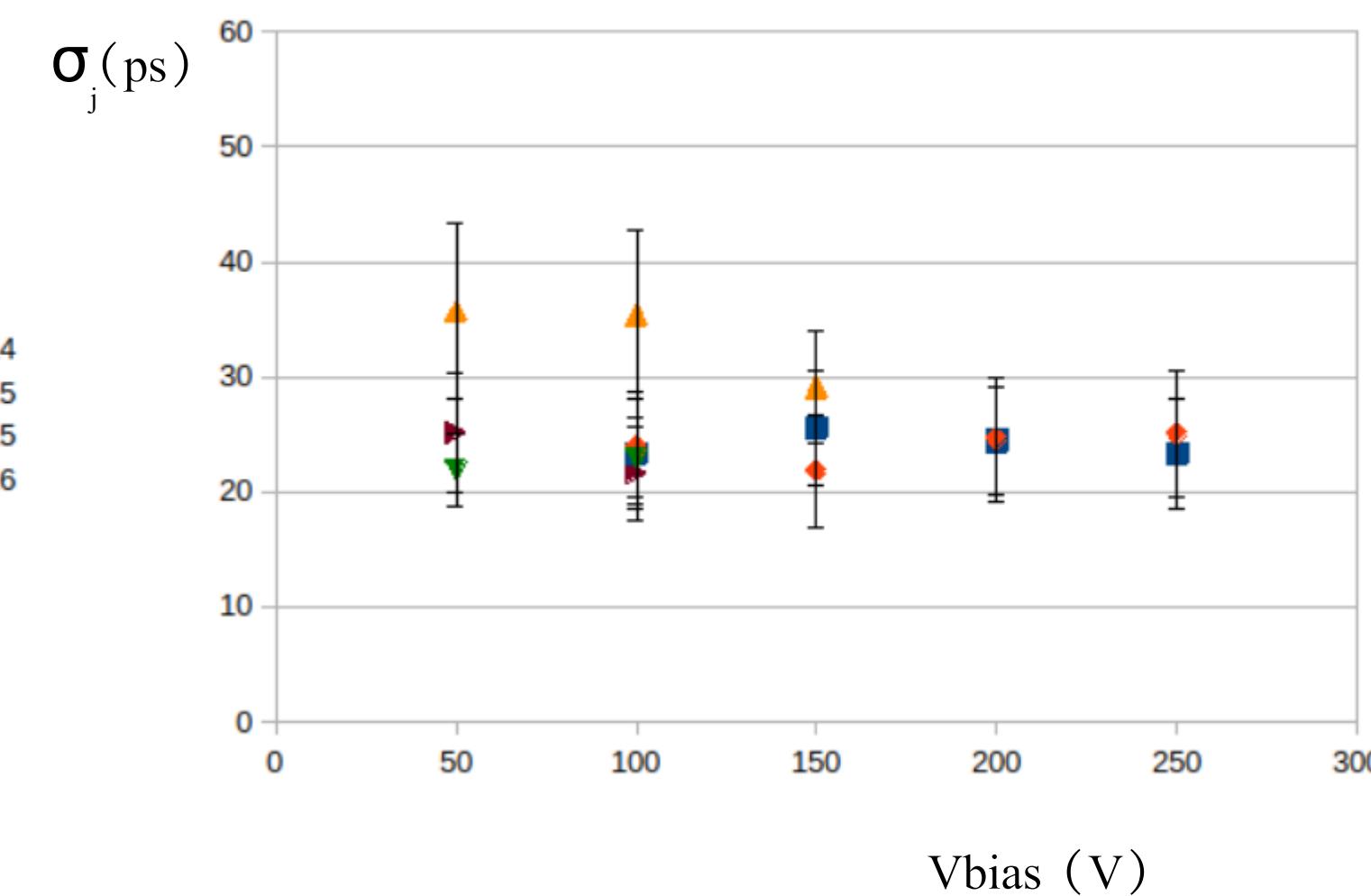
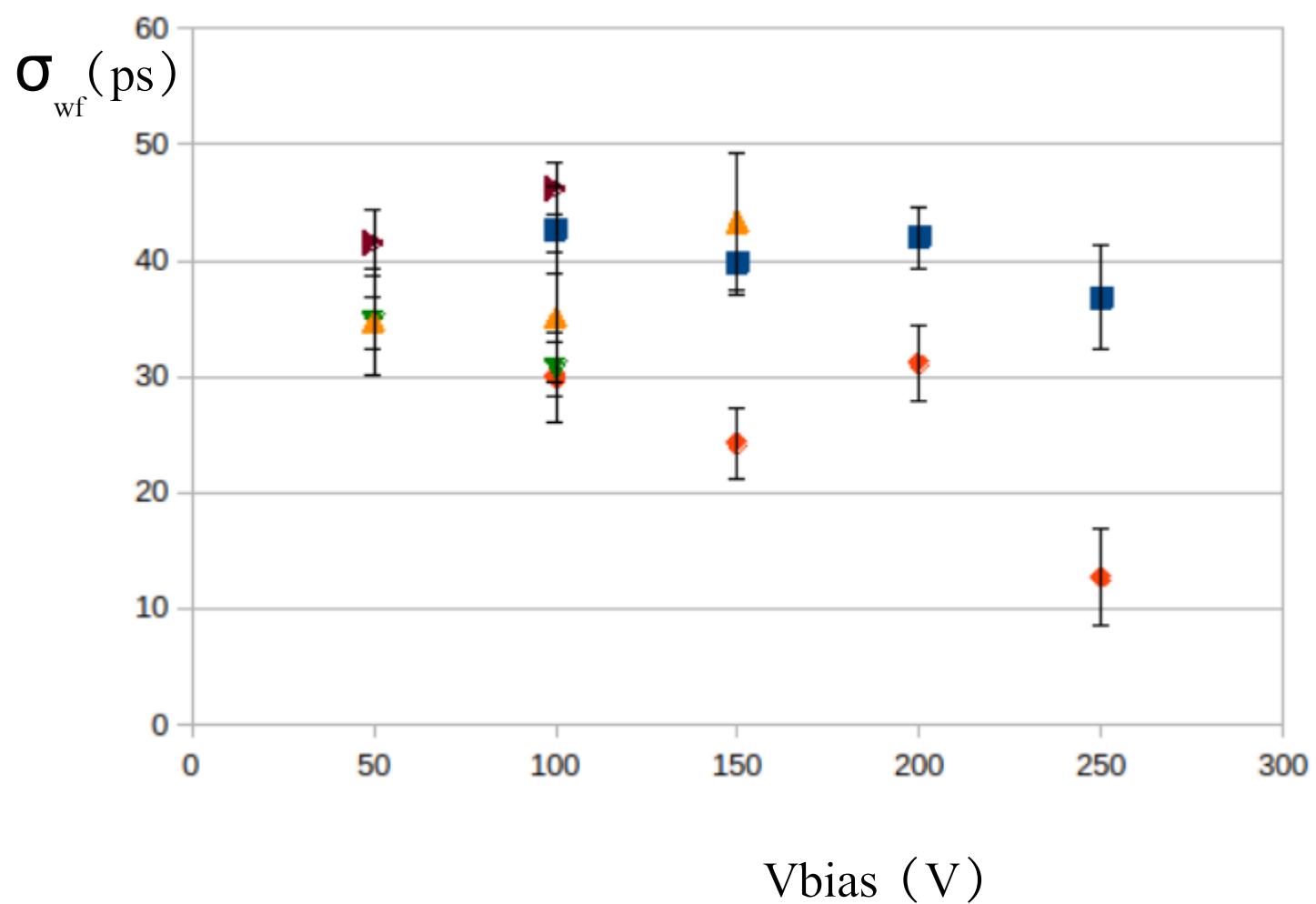
Irradiated at 8×10^{14} 1Mev n_{eq}/cm^2 - 2.3×10^{15} 1Mev n_{eq}/cm^2 - 4.8×10^{15} 1Mev n_{eq}/cm^2 - 1.0×10^{16} 1Mev n_{eq}/cm^2 at Ljubljana



Weighting field and jitter contribution at -20°C VS Bias voltage

Annealed 60 min at 80°C

Irradiated at 8×10^{14} 1Mev n_{eq}/cm² - 2.3×10^{15} 1Mev n_{eq}/cm² - 4.8×10^{15} 1Mev n_{eq}/cm² - 1.0×10^{16} 1Mev n_{eq}/cm² at Ljubljana

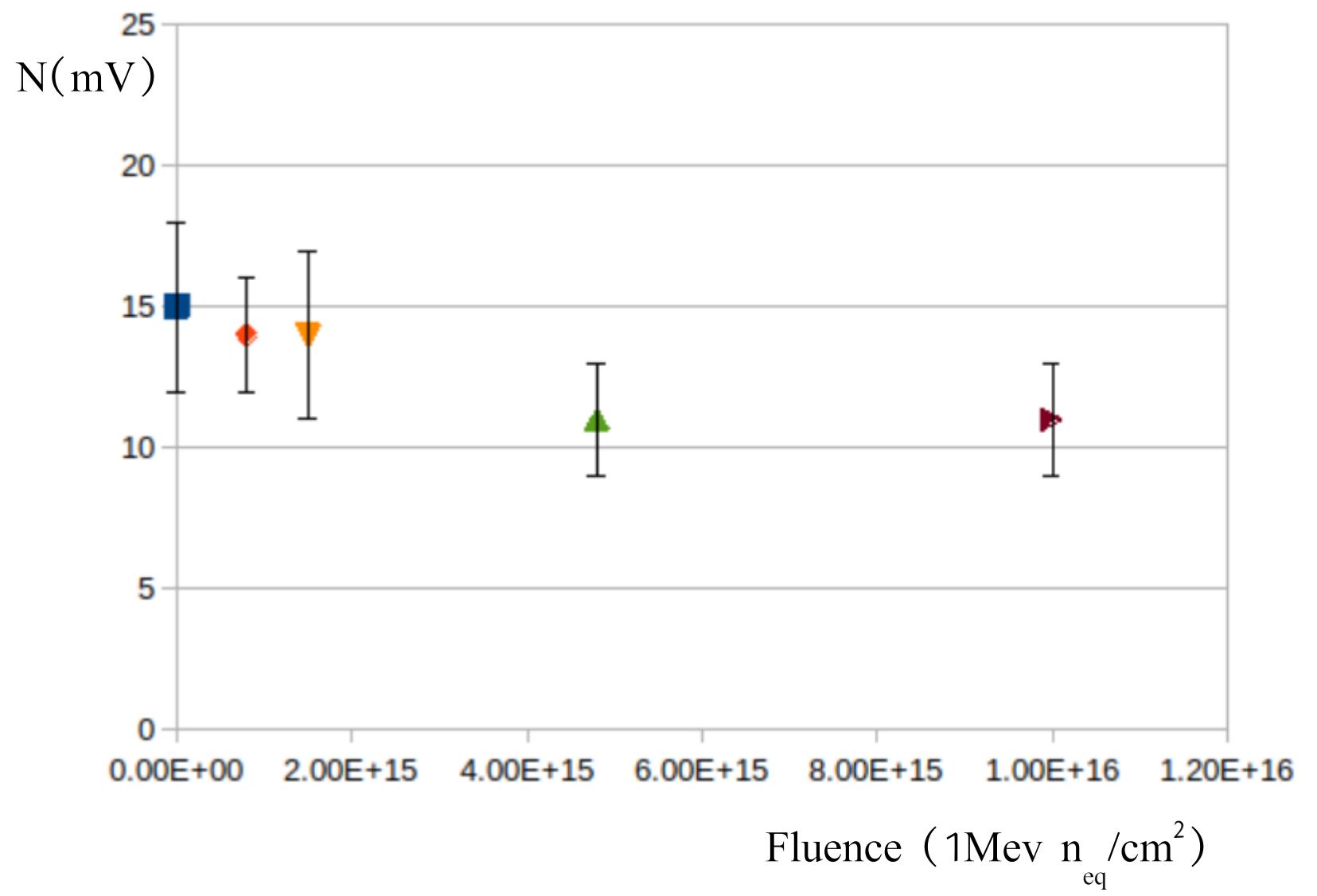


Conclusions

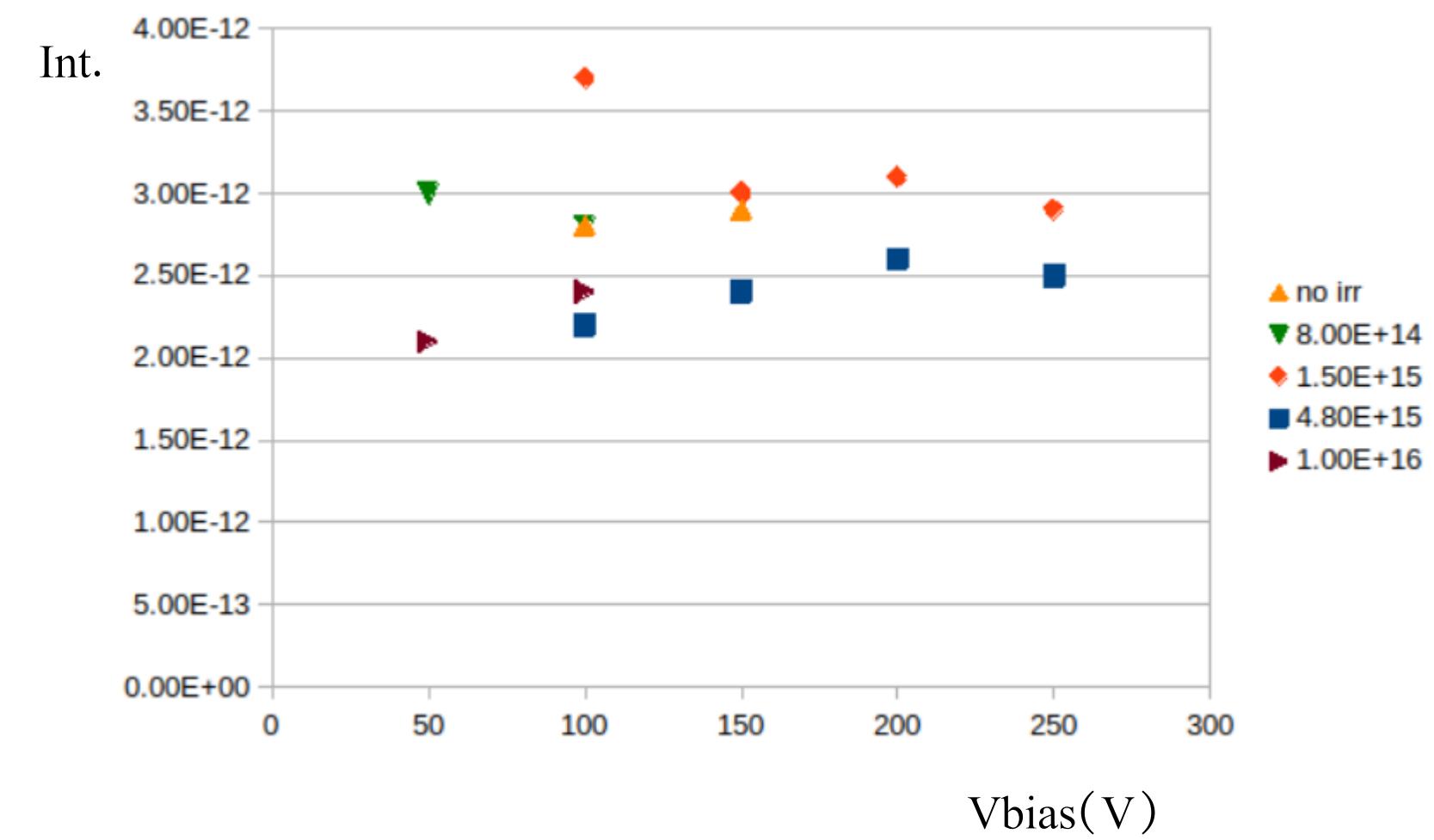
- We have reported data for 3D detector with thickness of 285 μm at 50,100,150,200,250 V_B at -20°C before and after n irradiation of 8×10^{14} 1MeV $n_{\text{eq}}/\text{cm}^2$ - 2.3×10^{15} 1Mev $n_{\text{eq}}/\text{cm}^2$ - 4.8×10^{15} 1Mev $n_{\text{eq}}/\text{cm}^2$ - 1.0×10^{16} 1Mev $n_{\text{eq}}/\text{cm}^2$
- Total time resolution of 50 ps, better resolution for intermediate fluences 8×10^{14} 1MeV $n_{\text{eq}}/\text{cm}^2$ - 2.3×10^{15} 1Mev $n_{\text{eq}}/\text{cm}^2$
- Behaviour of temporal resolution as a function of fluence attributable to weighting field contribute
- No remarkable difference for Vbias, for the last radiation dose it looks a bit better for 50V than for 100V

Backup - Analysis

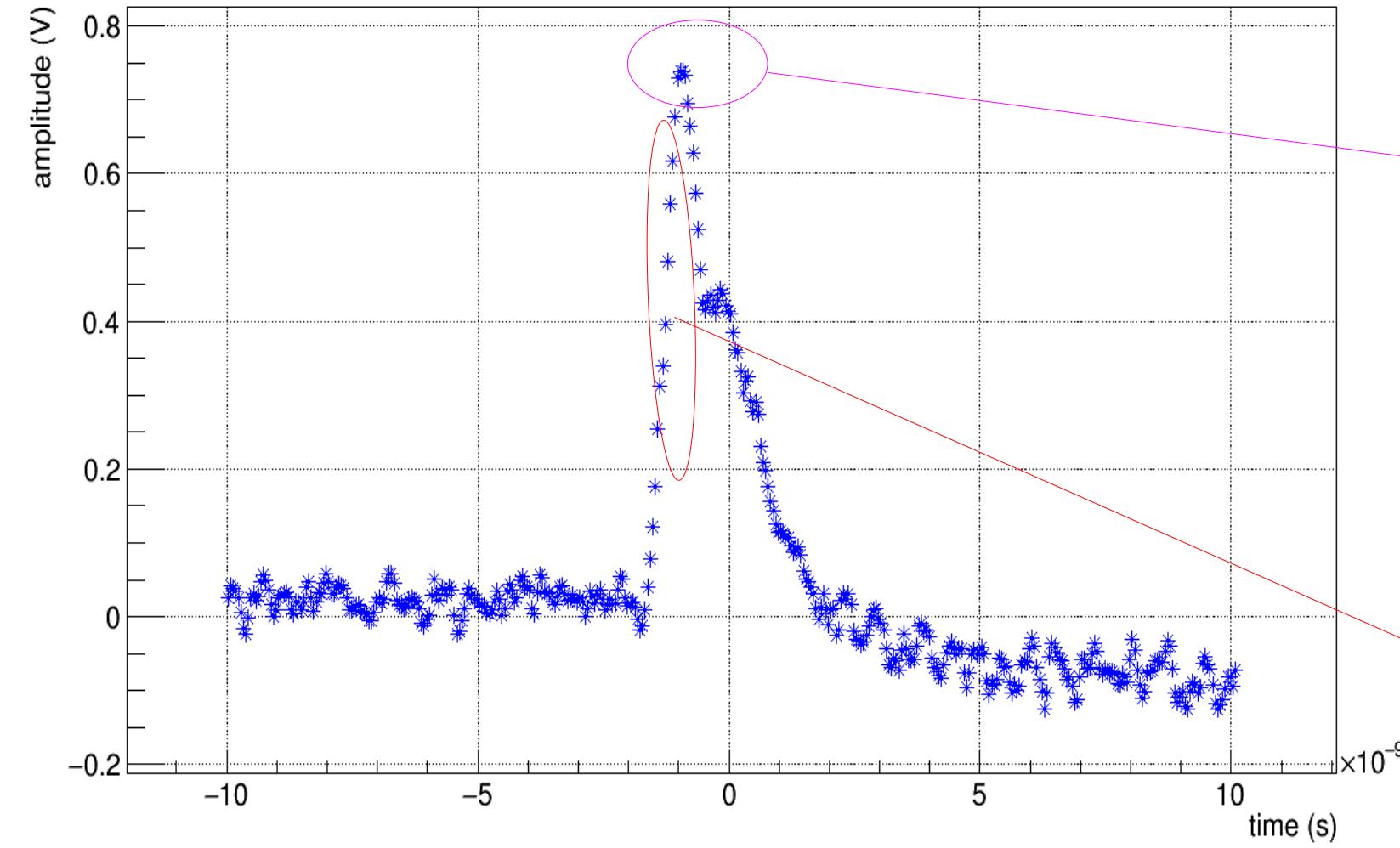
Noise



Charge Collection -20

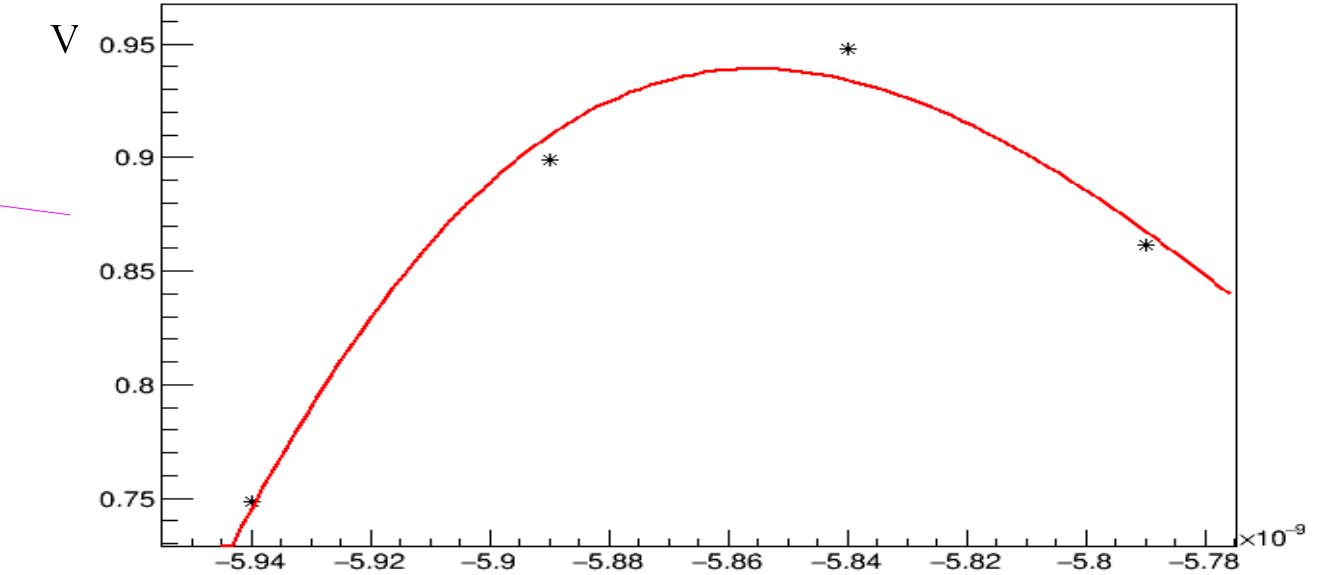


LGAD Waveform Analysis

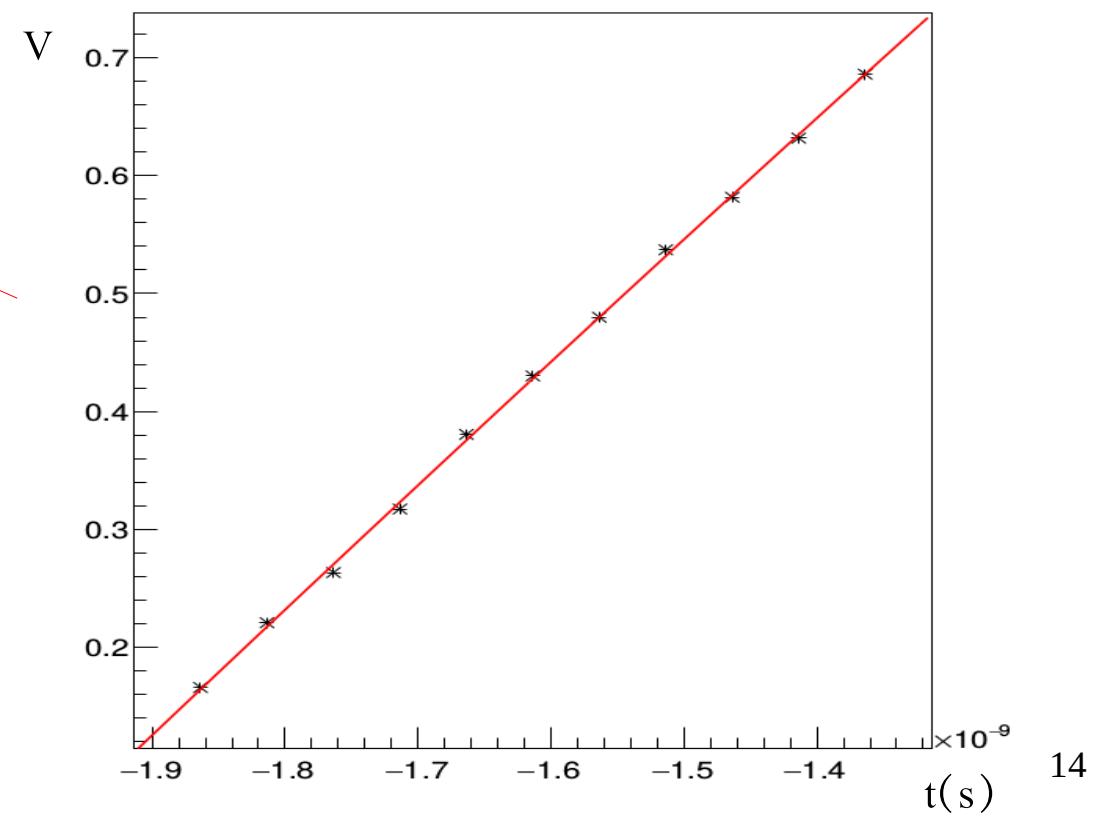


- 1) Noise estimation: gaus fit on the first 100 pt. (5 ns)
- 2) Offset correction
- 3) Landau fit around the maximum value in amplitude (4 pt.) and extrapolation of t_{MAX}
- 4) Landau fit (11 pt.) on the waveform rising
- 5) Extrapolation of t^*_{LGAD}

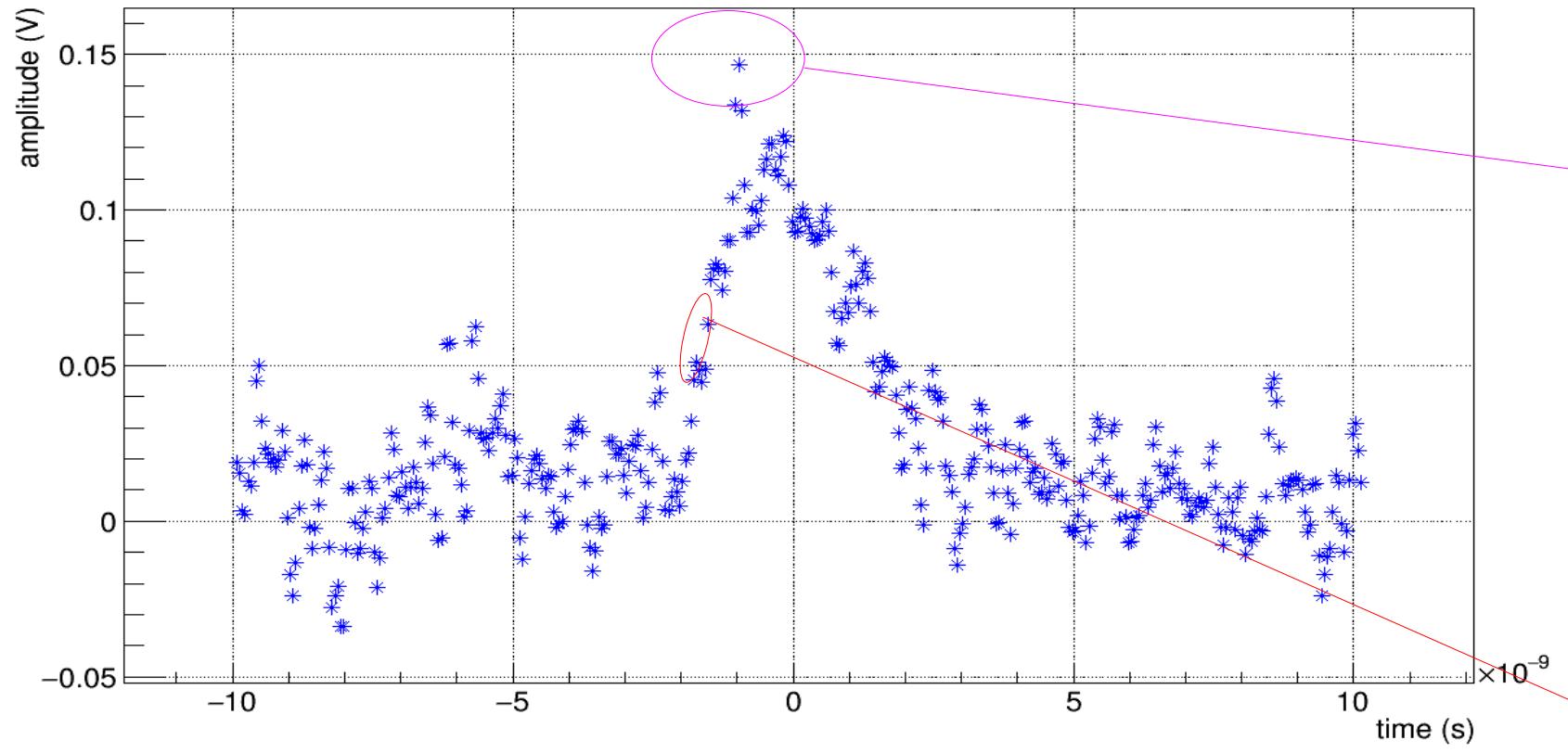
3)



4)

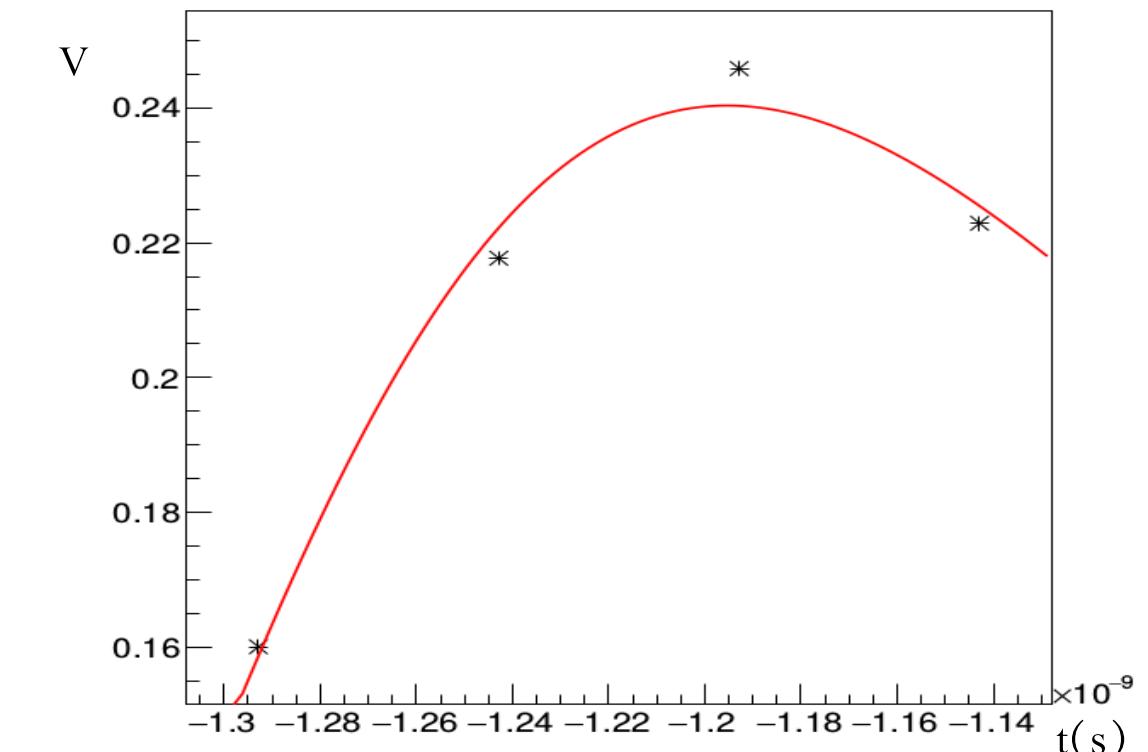


3D Waveform analysis



- 1) Noise estimation: gaus fit on the first 100 pt. (5 ns)
- 2) Offset correction
- 3) Landau fit around the maximum value in amplitude (4 pt.) and extrapolation of t_{MAX}
- 4) Linear fit (2 pt.) with the first point which crosses the threshold and the previous one
- 5) Extrapolation of t_{3D}^*

3)



4)

